TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (兀MOS)

2SK3758

Switching Regulator Applications

- Low drain-source ON resistance: RDS (ON) = 1.35 (typ.)
- High forward transfer admittance: $|Y_{fs}| = 3.5S$ (typ.)
- Low leakage current: $IDSS = 100 \mu A (VDS = 500 V)$
- Enhancement-mode: $V_{th} = 2.0 \sim 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_{D} = 1 \text{ mA}$)

/Circuit

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	500	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	500	V	
Gate-source voltage		V_{GSS}	±30	V	
	DC (Note 1)	I _D	5		
	Pulse (t = 1 ms) (Note 1)	l _{DP}	20		
Drain power dissipation (Tc = 25°C)		P_D	58	W	
Single pulse avalanche energy (Note 2)		E _{AS}	12	<u>۾</u>	
Avalanche current		l _{AR}	5	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	5.8	гJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	

Thermal Characteristics

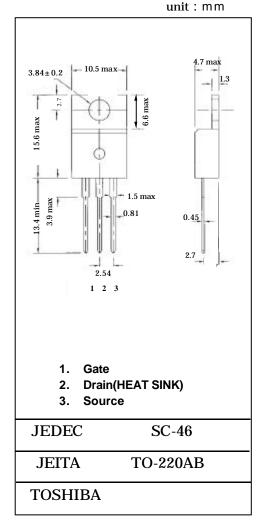
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.16	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on conditions that the channel temperature is below 150 °C.

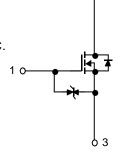
Note 2: V_{DD} = 90 V, T_{ch} = 25°C(initial), L = 0.82 mH, I_{AR} = 5 A, R_G = 25 Ω

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 2.0g(typ.)



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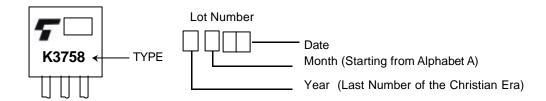
Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		l _{GSS}	$V_{GS} = \pm 25 V, V_{DS} = 0 V$	_	_	±10	μΑ
Gate-source bre	akdown voltage	V (BR) GSS	$I_D = \pm 10 \mu A, V_{GS} = 0 V$	±30	_		V
Drain cut-off curi	rent	I _{DSS}	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μΑ
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500	_	_	V
Gate threshold v	oltage	V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	_	4.0	V
Drain-source ON	l resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$	_	1.35	1.50	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 2.5 \text{ A}$	1.5	3.5	_	S
Input capacitance		C _{iss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	550	_	pF
Reverse transfer capacitance		C _{rss}		_	7	_	
Output capacitance		Coss		_	70	_	
Switching time	Rise time	t _r	V_{GS} $V_{DD} \simeq 225$ $V_{DD} \simeq 225$	_	10		
	Turn-on time	t _{on}		_	20		
	Fall time	t _f		_	10		ns
	Turn-off time	t _{off}	Duty ≦ 1%, t _w = 10 μs	_	50	_	
Total gate charge		Qg		_	16	_	
Gate-source charge		Q_{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		10		nC
Gate-drain charge		Q_{gd}			6		

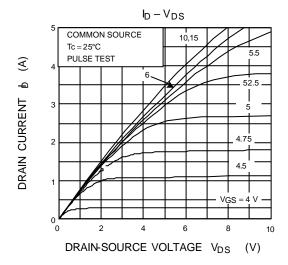
Source-Drain Ratings and Characteristics (Ta = 25°C)

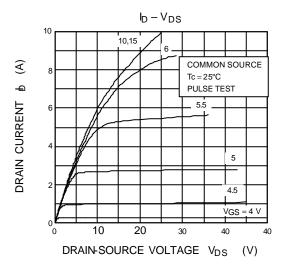
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	l _{DR}	_	_		5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)	V_{DSF}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 A, V_{GS} = 0 V,$	_	1400	_	ns
Reverse recovery charge	Q _{rr}	$dI_{DR}/dt = 100 A/\mu s$	_	9	_	μС

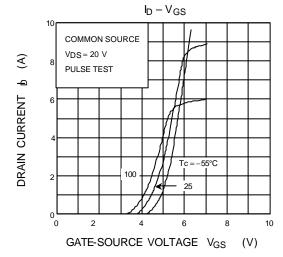
Marking

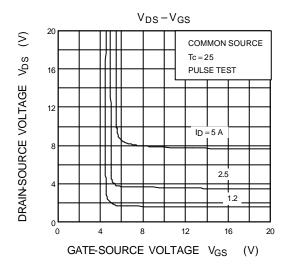


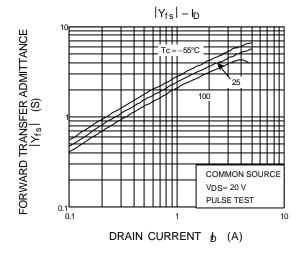
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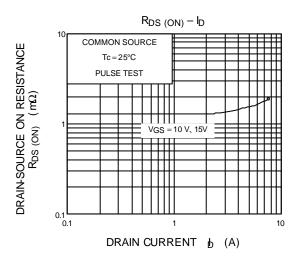


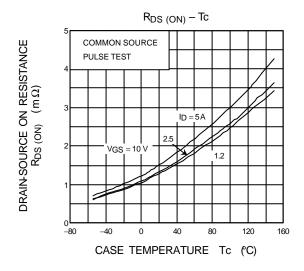


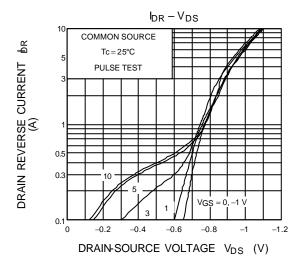


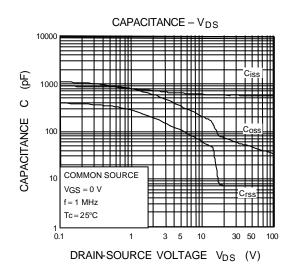


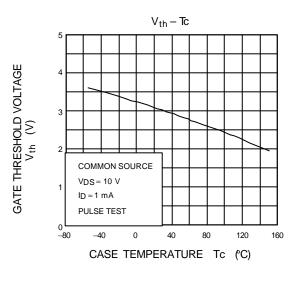


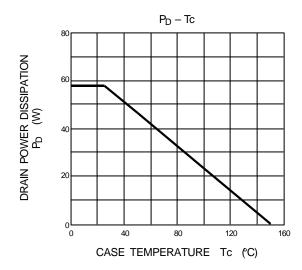


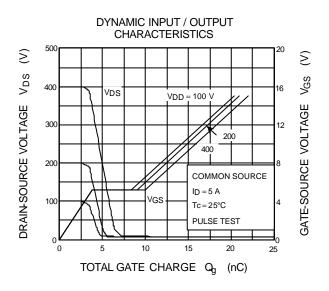


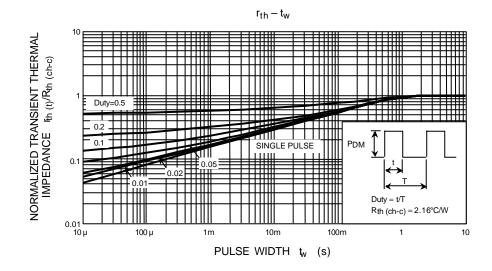


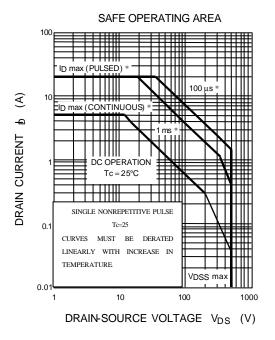


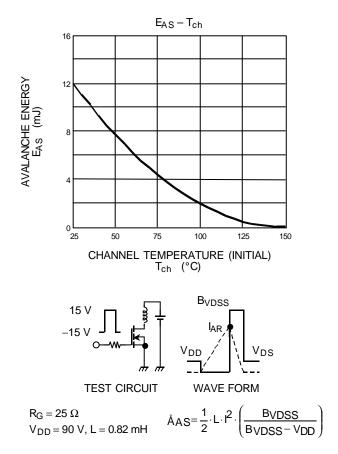












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